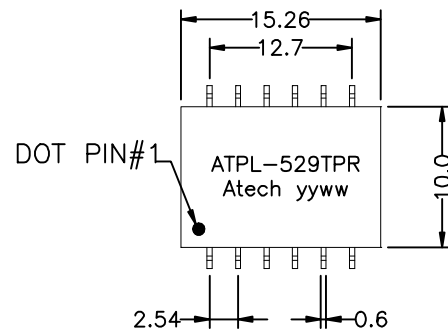
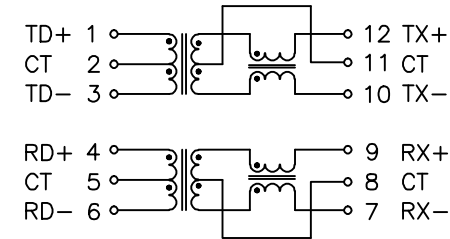


SUGGESTED PAD LAYOUT



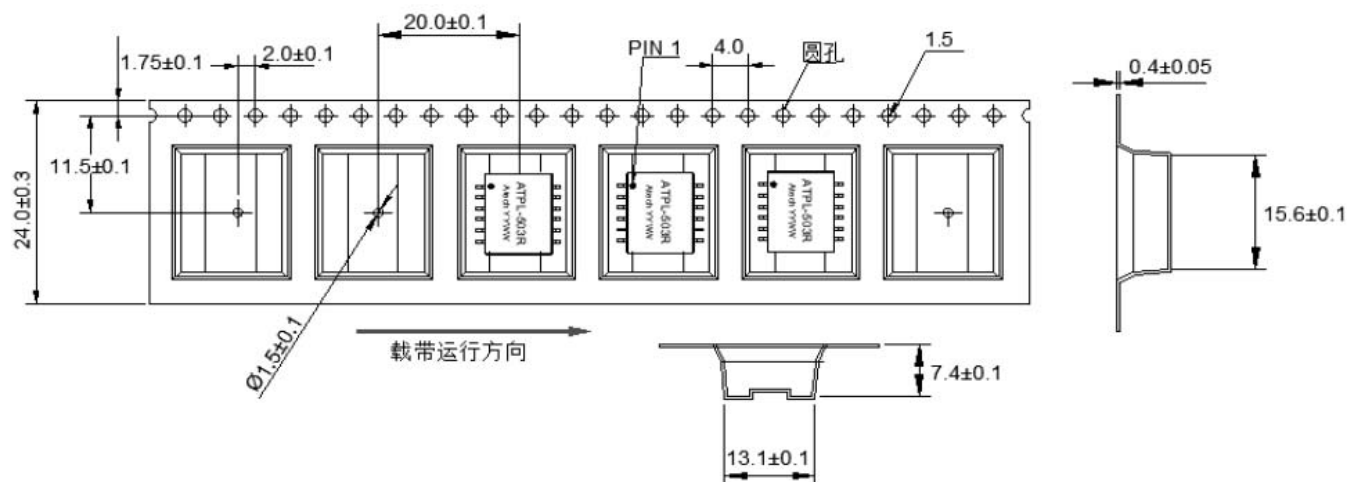
ELECTRICAL CHARACTERISTICS @25°C:

1. INSULATION HI-POT(PRI./SEC.) : 1500Vrms, 1mA, 60SEC
2. TURN RATIO ($\pm 3\%$) : TX = 1CT : 1CT
RX = 1CT : 1CT
3. OCL : 350uH MIN @100kHz, 0.1V, 35mA DC BIAS,
4. INSERTION LOSS : 1-100MHz = -1.0dB MAX.
5. RETURN LOSS (dB MIN.) : 1-30MHz 40MHz 50MHz 60-80MHz 80-100MHz
-18 -14.4 -13.1 -12 -10
6. CROSS TALK : 1-100MHz = -30dB MIN.
7. COMMON MODE REJECTION : 1-100MHz = -30dB MIN.
8. DCR : 1.2 Ω MAX.
9. OPERATING TEMPERATURE RANGE : -40°C~+85°C
10. Compliant with IEEE 802.3at
11. Suitable for End-span poE applications with 1000mA current capability
12. RoHS COMPLIANT

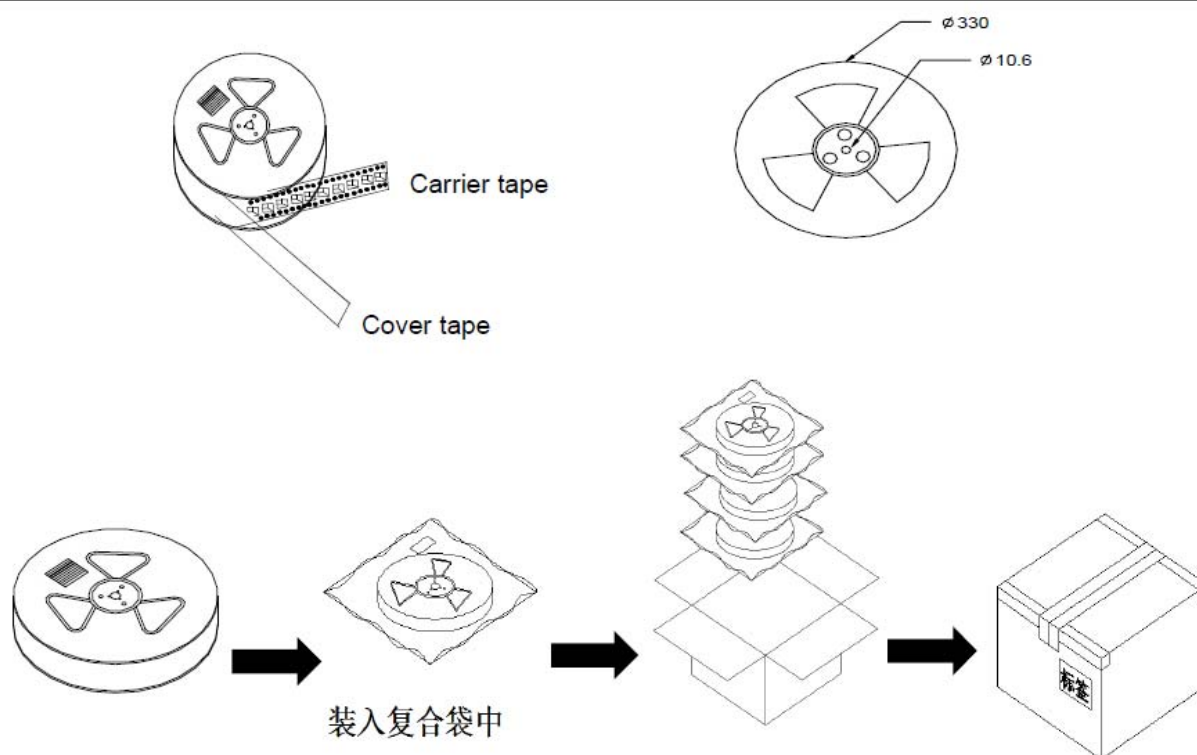
UNLESS OTHERWISE SPECIFIED ALL TOLERANCES ARE $\pm 0.25\text{mm}$

							TITLE 10/100 BASE-T PoE* TRANSFORMER	
							DWG. NO. ATPL-529TPR	
	RELEASE	03/08/2019	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY	
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE	P/N:	SHEET 1 of 1
REVISIONS						03/08/19	DRAW SHIRLEY	

1. Package :



PACKAGE



备注：包材（卷盘、上封带、载带）变更为防静电材料，

防静电标准： $10^4 \leq R_s < 10^{11} \Omega$ ，期限是1-3年。

零件包装符合EIA-481 standard(拉力 $0.26N \sim 1.3N$)。

Product	PCS/Reel	PCS/Box	Product No.	Weight(g/pcs)
SMD 12 PIN Series	400	400*6=2400		1

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max	3°C/second max
Preheat Temperature Min (Tmin) Temperature Min (Tsmax) Time (Tmin to Tsmax) (ts)	100°C 150°C 60-120seconds	150°C 200°C 60-180seconds
Time maintained above Temperature (TL) Time (tL)	183°C 60-150seconds	217°C 60-150seconds
Peak Temperature (Tp)	225°C	260°C
Time within 5°C of actual Peak Temperature (Tp) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max